

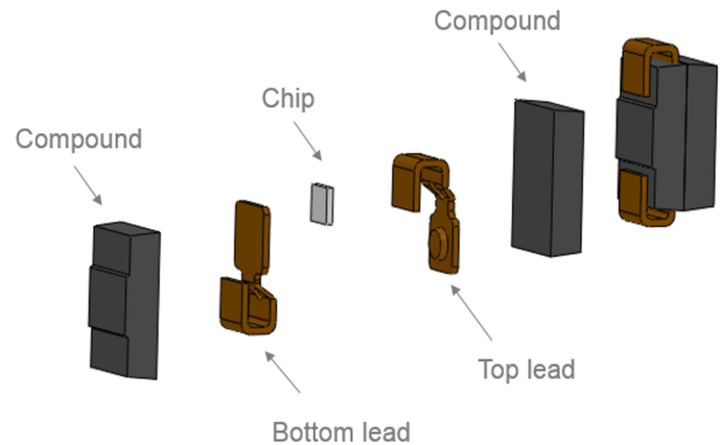
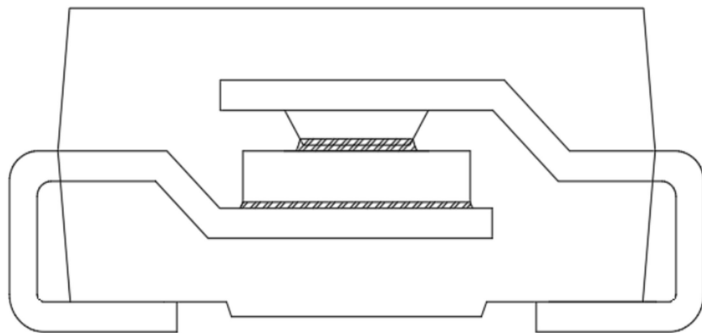


SMA

## 1: Certification

- System:
  - IATF 16949
  - ISO9001
  - ISO14001
  - ISO45001
- ROHS/REACH/ELV:
  - Lead frame、Solder, Molding compound、Post plating.
- UL 94: V-0
- MSL : level 1
- Whisker Test: JESD 201 class 2
- Solder bath temperature : 260°C maximum, 10 s

## 2: Internal Structure Diagram



### Meet Die Size

	Lead Pad(mm)	Die size(mil)	Wafer thickness (um)
Max	1.80	70.00	350.00
Min	0.80	32.00	110.00

## 3: Production line advantage

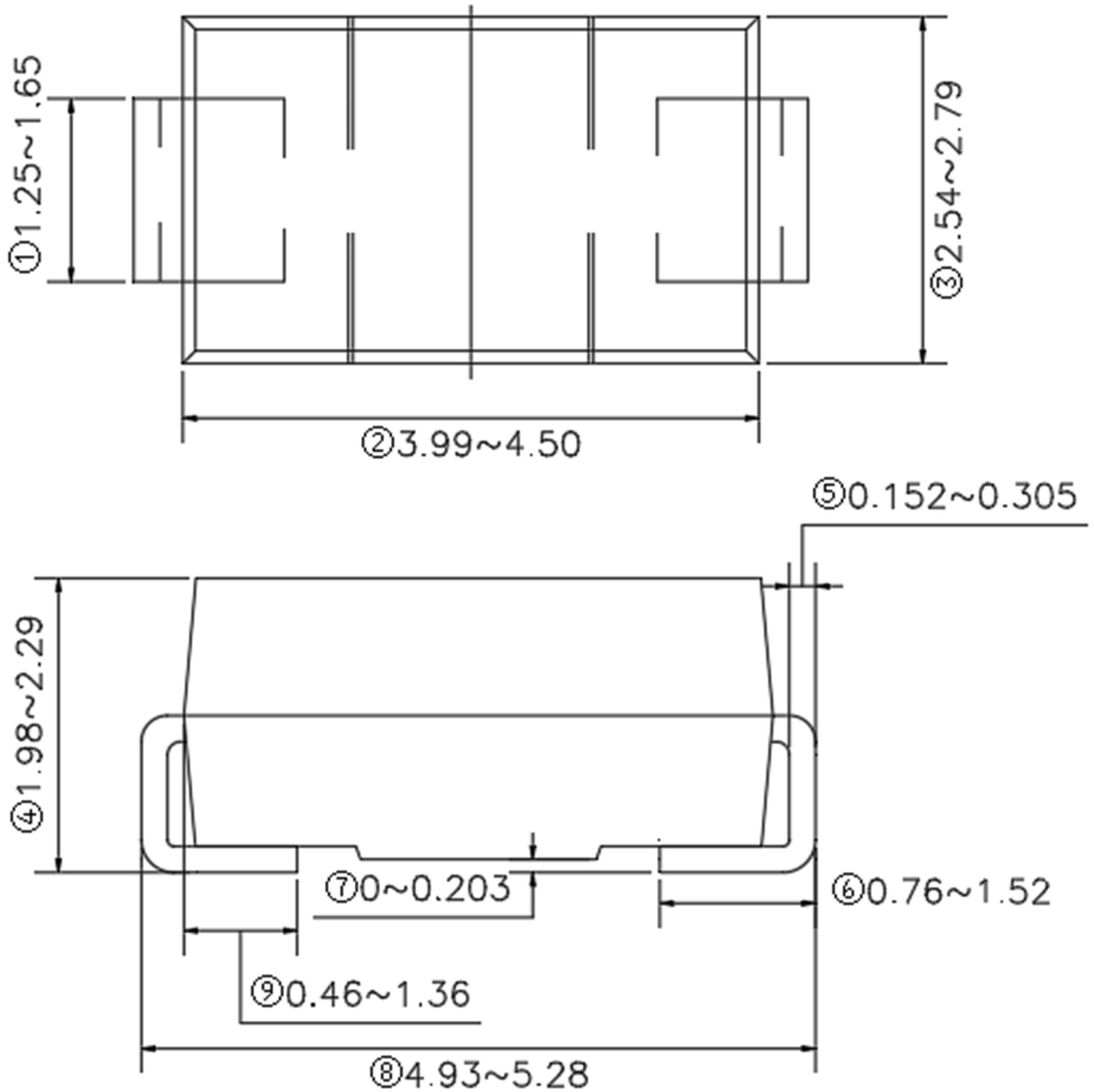
- 100% AOI in TMTT.
- Automated production line for all process.

## 4: Reliability Experiment

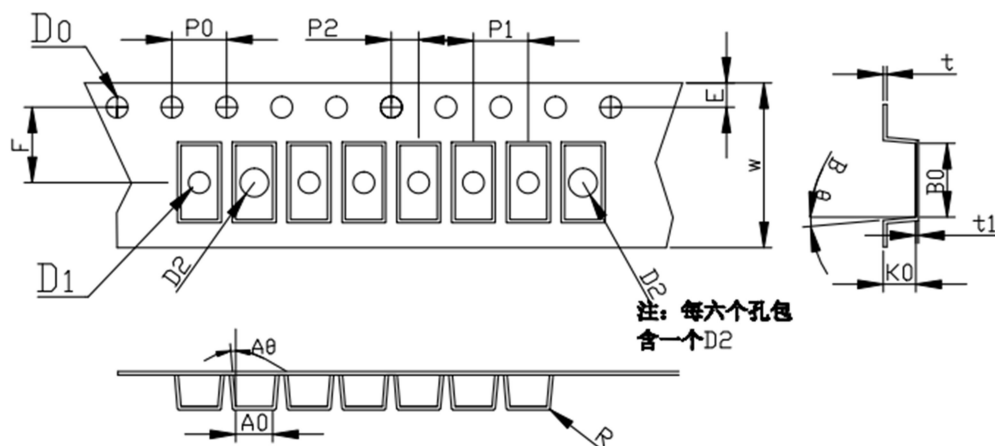
Test	Test Condition
HAST	80%VR/130°C/85%R.H.
Temp. Cycling	1000 cycles form -55°to 150°C
UHAST	96 hours at Ta = 130°C, RH = 85%
HTRB	1000 hours 150°
RSH	260°C , 10 s

## 5: Package Outline Dimensions in millimeters

### 5.1 POD



## 5.2 Package (tape & carrier) Dimensions in millimeters



Symbol	Spec	Symbol	Spec
W	$12.00^{+0.30}_{-0.10}$	A0	$2.59 \pm 0.10$
E	$1.75 \pm 0.10$	B0	$5.33 \pm 0.10$
F	$5.50 \pm 0.05$	K0	$2.36 \pm 0.10$
D0	$1.50^{+0.10}_{-0.00}$	10*P0	$40.00 \pm 0.20$
D1	$1.50^{+0.25}_{-0.00}$	Aθ	10.5" MAX
D2	$1.70^{+0.05}_{-0.00}$	Bθ	4" MAX
P0	$4.00 \pm 0.10$	R	0.130MAX
P1	$4.00 \pm 0.10$	t	$0.23 \pm 0.03$
P2	$2.00 \pm 0.05$	t1	$\geq 0.10$